L Number	Hits	Search Text	DB	Time stamp
-	644	(216/13).CCLS.	USPAT	2003/07/11 15:32
-	481	(216/18).CCLS.	USPAT	2003/08/26 16:57
-	284	(216/17).CCLS.	USPAT	2003/07/11 11:24
-	41	(216/15).CCLS.	USPAT	2003/08/25 11:43
-	170	(216/16).CCLS.	USPAT	2003/07/11 11:25
-	65	(216/19).CCLS.	USPAT	2003/07/30 13:17
-	602	(216/20).CCLS.	USPAT	2003/07/11 11:26
-	768	(29/825).CCLS.	USPAT	2003/07/11 11:27
-	337	(29/829).CCLS.	USPAT	2003/07/11 11:27
-	788	(29/830).CCLS.	USPAT	2003/07/11 11:27
-	250	(29/831).CCLS.	USPAT	2003/08/27 14:08
-	919	(29/846).CCLS.	USPAT	2003/07/11 11:29
-	970	(29/832).CCLS.	USPAT	2003/07/11 11:30
-	90	(29/835).CCLS.	USPAT	2003/07/11 11:31
-	381	printing with (devices or components) with (circuit adj board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/30 12:26
-	78	(method and multilayer and (circuit adj board)).ti.	USPAT; US-PGPUB	2003/07/11 13:08
-	159	(method and multilayer and (circuit adj board)).ti.	JPO	2003/07/11 13:09
-	8	((vias or holes) and (circuit adj board)).ti.	JPO	2003/07/11 13:10
-	66	((vias or holes) and (circuit adj board)).ti.	USPAT; US-PGPUB	2003/07/11 13:10
-	74	(etch-resist$3 or (etch adj resist$3)) adj ink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/11 15:33
-	55	((solder adj mask) with printing).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/14 10:17
-	152	((solder adj mask) with printing) and (circuit adj board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 15:23
-	223	(circuit adj board).ti. and (plating near5 thickness)	USPAT; US-PGPUB	2003/08/26 15:26
-	111	(circuit adj board).ti. and mask and (plating near5 thickness)	USPAT; US-PGPUB	2003/07/14 10:39
-	49	(circuit adj board).ti. and mask and printing.clm.	USPAT; US-PGPUB	2003/07/14 10:40
-	241	(circuit adj board).ti. and ((plating or solder) adj mask)	USPAT; US-PGPUB	2003/07/14 10:41
-	15	(circuit adj board).ti. and (press-bonding)	USPAT; US-PGPUB	2003/07/14 10:41
-	563	(circuit adj board).ti. and (laminating)	USPAT; US-PGPUB	2003/07/14 10:42
-	228	print$3 and ((direct or off-set) adj mode)	USPAT; US-PGPUB	2003/07/14 10:44
-	216	((electrophotographic or electro-photographic) adj print$3) and (circuit adj board)	USPAT; US-PGPUB	2003/07/14 10:49
-	7	((((ink adj jet)or ink-jet) adj print$3) and (circuit adj board)).ab.	USPAT; US-PGPUB	2003/07/14 10:49
-	222	((lithographic) adj print$3) and (circuit adj board)	USPAT; US-PGPUB	2003/07/14 10:50
-	341	(printed adj (resistor or cappacitor or inductor))	USPAT; US-PGPUB	2003/07/14 10:51
-	492	(printed adj (resistor$1 or cappacitor$1 or inductor$1))	USPAT; US-PGPUB	2003/07/14 10:52
-	0	(printed with (resistor$1 and cappacitor$1 and inductor$1))	USPAT; US-PGPUB	2003/07/14 10:52
-	439	printed adj resistor$1	USPAT; US-PGPUB	2003/07/14 11:40

-	62	printed adj inductor$1	USPAT; US-PGPUB	2003/07/14 10:54
-	112	printed adj capacitor$1	USPAT; US-PGPUB	2003/07/14 10:53
-	245	((printed adj resistor$1) or (printed adj capacitor$1) or (printed adj inductor$1)) and (circuit adj board)	USPAT; US-PGPUB	2003/07/14 10:56
-	424	printed adj resistor$1	EPO; JPO; DERWENT; IBM_TDB	2003/07/14 11:41
-	1436	(copper adj (clad or cladding)) and ((circuit or wiring) adj board)	EPO; JPO; DERWENT; IBM_TDB	2003/07/14 11:43
-	3145	(copper adj (clad or cladding)) and ((circuit or wiring) adj board)	USPAT; US-PGPUB	2003/07/14 11:44
-	1151	((copper adj (clad or cladding)) and ((circuit or wiring) adj board)) and (mask$3 and etch$3)	USPAT; US-PGPUB	2003/07/14 11:44
-	2388	(copper adj (clad or cladding)) and ((circuit or wiring) adj board) and etch$3	USPAT; US-PGPUB	2003/07/14 11:45
-	10	(copper adj (clad or cladding)) and ((circuit or wiring) adj board) and (printed adj (resistor$1 or capacitor$1 or inductor$1))	USPAT; US-PGPUB	2003/07/14 11:48
-	1077	(copper adj (clad or cladding)) and ((circuit or wiring) adj board) and ((holes or vias) with (plated or plating))	USPAT; US-PGPUB	2003/07/14 11:50
-	32	((copper adj (clad or cladding)) and ((circuit or wiring) adj board)) and (seed adj layer)	USPAT; US-PGPUB	2003/07/14 11:51
-	384	((printing or screening) with (mask)) and (circuit adj board).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/30 12:28
-	240	(216/39).CCLS.	USPAT	2003/07/30 13:19
-	760	(216/41).CCLS.	USPAT	2003/07/30 13:18
-	353	(216/33).CCLS.	USPAT	2003/07/30 13:22
-	100	(216/36).CCLS.	USPAT	2003/07/30 13:55
-	96092	((circuit or wiring) adj board).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 11:53
-	260	(((circuit or wiring) adj board).ti.) and print$3 near2 traces	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 12:20
-	2	("5826329").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 12:16
-	9	("2582685" | "3350250" | "3778899" | "4343083" | "4403410" | "4991287" | "5013397" | "5184111" | "5426850").PN.	USPAT	2003/08/25 11:58
-	1	5826329.URPN.	USPAT	2003/08/25 12:16
-	2	("5932280").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 12:16
-	5	("3909680" | "4722765" | "4991287" | "5379190" | "5826329").PN.	USPAT	2003/08/25 12:17
-	0	5932280.URPN.	USPAT	2003/08/25 12:18
-	0	5932280.URPN.	USPAT	2003/08/25 12:18
-	9	(((circuit or wiring) adj board).ti.) and direct adj printing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 12:22

-	58	(((circuit or wiring) adj board).ti.) and offset adj printing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 12:48
-	17	(((circuit or wiring) adj board).ti.) and lithographic adj printing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 12:23
-	3	(((circuit or wiring) adj board).ti.) and off-set adj printing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 12:24
-	1657	(((circuit or wiring) adj board).ti.) and screen adj printing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 12:25
-	103	(((circuit or wiring) adj board).ti.) and (screen adj printing) same (resistor$1 or capacitor$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 12:25
-	24	(((circuit or wiring) adj board).ti.) and (screen adj printing) same (resistor$1 and capacitor$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 12:33
-	12	(((circuit or wiring) adj board).ti.) and ((ink-jet or inkjet) adj printing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 12:30
-	1303	(((circuit or wiring) adj board).ti.) and (solder adj resist) with print$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 12:49
-	165	(((circuit or wiring) adj board).ti.) and (solder adj resist) with print$3 with (inkjet or lithographic or screen or relief or press)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 12:55
-.	16	(((circuit or wiring) adj board).ti.) and (solder adj resist) with print$3 with (inkjet or lithographic or relief or press)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 12:58
-	1	(((circuit or wiring) adj board).ti.) and (printing with (press and lithographic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 16:30
-	13	(printing) with (fusable adj ink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 14:39
-	4	((printing) and (fusable adj ink)) and (silver or Ag or palladium or Pd)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 14:39
-	330	(printing) with (fusible adj ink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 14:39

-	83	((printing) and (fusible adj ink)) and (silver or Ag or palladium or Pd)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 14:44
-	3	((printing) and (fusible adj ink)) and (silver or Ag or palladium or Pd) and (circuit adj board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 14:42
-	13	((printing) and (fusible adj ink)) and (palladium or Pd)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 15:27
-	377	(circuit adj board).ti. and (plat$3 same thickness) and mask$3	USPAT; US-PGPUB	2003/08/26 15:51
-	0	"09890471"	USPAT; US-PGPUB	2003/08/26 15:52
-	603	(216/20).CCLS.	USPAT	2003/08/26 17:09
-	58	((216/20).CCLS.) and (circuit adj board).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 16:58
-	7	(method and (multi-layer or multilayer) and (circuit adj board)).ti. and ((double adj sided) or double-sided).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 14:19
-	39	(method and (multi-layer or multilayer) and (circuit adj board)).ti. and ((double adj sided) or double-sided)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 17:11
-	37	3660726.URPN.	USPAT	2003/08/26 17:13
-	649	(29/852).CCLS.	USPAT	2003/08/27 14:09
-	611	(method and (multi-layer or multilayer) and (circuit adj board)).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 14:21
-	1380	((multi-layer or multilayer) and (circuit adj board)).ti.	USPAT; US-PGPUB; JPO	2003/08/27 14:23
-	333	((multi-layer or multilayer) and (circuit adj board)).ti.	USPAT; US-PGPUB	2003/08/27 14:23
-	27	((solder adj mask) with printing) and (circuit adj board).ti.	USPAT; US-PGPUB	2003/08/27 15:26
-	2	("4991287").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 16:22
-	2	("2582685" | "4403410").PN.	USPAT	2003/08/27 16:22